

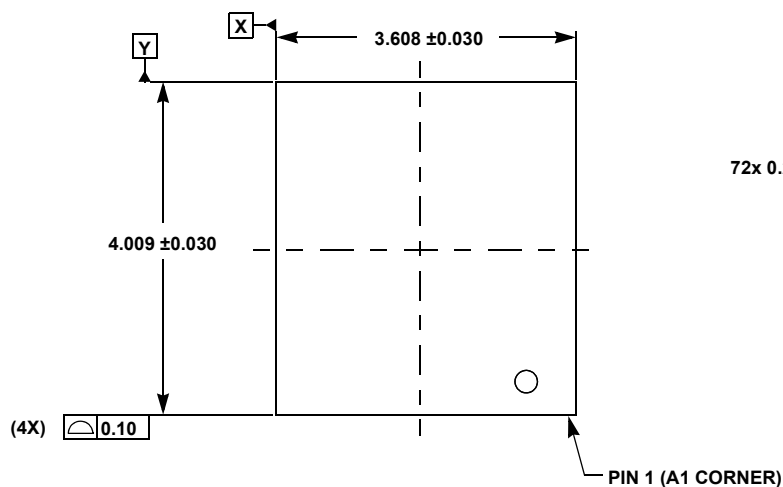
Plastic Packages for Integrated Circuits

Package Outline Drawing

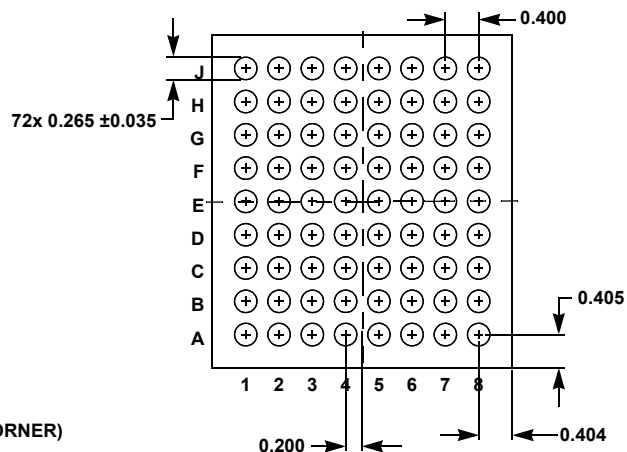
W8x9.72B

72 Ball Wafer Level Chip Scale Package (WLCSP 0.4mm Pitch)

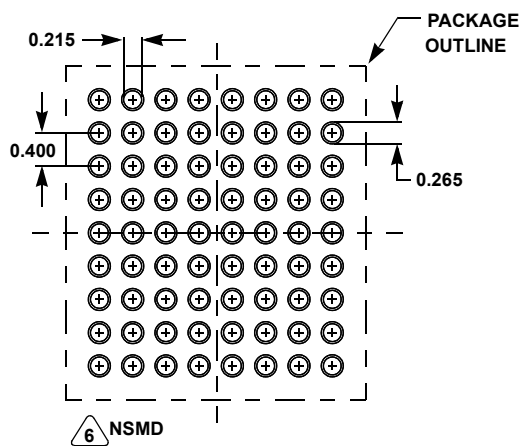
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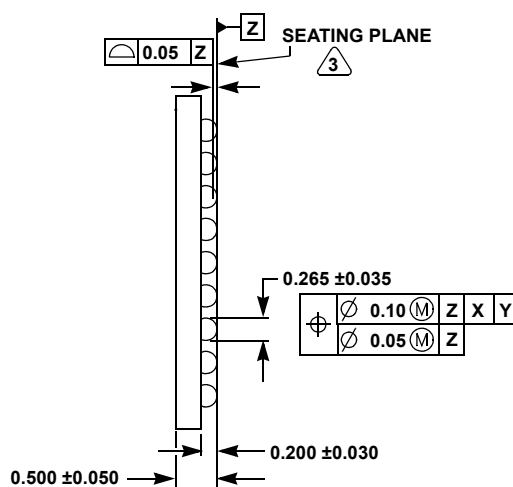
TOP VIEW



BOTTOM VIEW



RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerance and tolerance per ASMEY 14.5 - 1994.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z .
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask defined pad design per Intersil. Techbrief [TB451](#).